

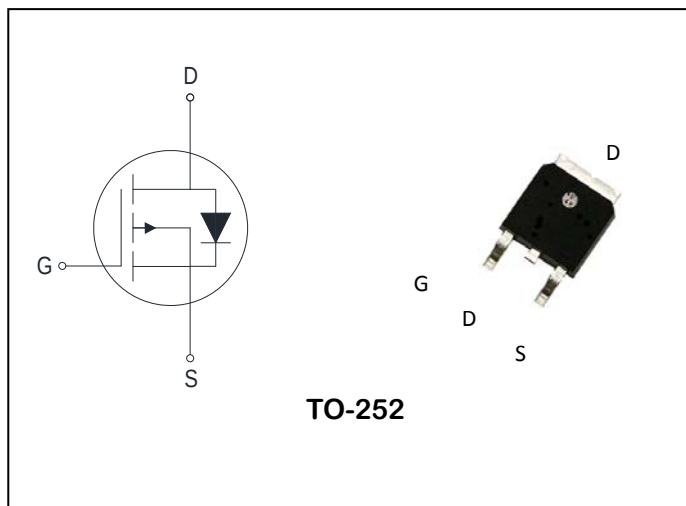
P-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

V_{DSS}	I_D	$R_{DS(ON)}$ (m Ω)
-60V	-30A	40m Ω

Features:

- Low Gate Charge for Fast Switching Application
- Fast Switching
- High Power and current handling capability
- Green Device Available



Description:

The ADM30P06E is the high cell density trench P-ch MOSFETs, design to provide excellent $R_{DS(ON)}$ with low gate charge. provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Ratings	Unit
Common Ratings				
V _{DSS}	Drain-Source Voltage		-60	V
V _{GSS}	Gate-Source Voltage		±20	
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to150	°C
I _S	Diode Continuous Forward Current	T _C =25°C	-30	A
Mounted on Large Heat Sink				
I _{DM}	300μs Pulse Drain Current Tested ⁽²⁾	T _C =25°C, V _{GS} =-10V	-120	A
I _D	Continuous Drain Current ⁽¹⁾	T _C =25°C, V _{GS} =-10V	-30	A
		T _C =100°C V _{GS} =-10V	-18	A
P _D	Maximum Power Dissipation	T _C =25°C	60	W

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
R_{thJC}	Thermal resistance junction-case max ⁽¹⁾	2.72	$^\circ\text{C/W}$
R_{thJA}	Thermal resistance junction-ambient max ⁽¹⁾	62	$^\circ\text{C/W}$

Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
On/off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250uA	-60	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -60V, V _{GS} =0V T _J =25°C	--	--	-1	uA
		V _{DS} =-48V,V _{GS} =0V T _J =125°C	--	--	-10	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250uA	-1.0	-1.8	-3.0	V
I _{GSS}	Gate Leakage Current	V _{GS} = ± 20V, V _{DS} =0V	--	--	± 100	nA
R _{DS(ON)}	Drain-SourceOn-stateResistance ⁽²⁾	V _{GS} = -10V, I _{DS} =-4A	--	28	40	mΩ
		V _{GS} = -4.5V, I _{DS} =-3A	--	32	55	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} = -25V, Frequency=1.0MHz	--	3263	--	pF
C _{oss}	Output Capacitance		--	140	--	
C _{rss}	Reverse Transfer Capacitance		--	80	--	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time ⁽¹⁾	V _{DD} =-30V, I _D = -1A, V _{GS} = -10V, R _{GEN} =3 Ω R _L =15 Ω	--	8	--	ns
t _r	Turn-on Rise Time ⁽¹⁾		--	6	--	
t _{d(OFF)}	Turn-off Delay Time ⁽¹⁾		--	30	--	
t _f	Turn-off Fall Time ⁽¹⁾		--	7	--	
Q _g	Total Gate Charge ⁽¹⁾	V _{DS} =-20V, V _{GS} = -10V, I _{DS} =-4A	--	64	--	nC
Q _{gs}	Gate-Source Charge ⁽¹⁾		--	6.7	--	
Q _{gd}	Gate-Drain Charge ⁽¹⁾		--	13	--	
Diode Characteristics						
V _{SD}	Diode Forward Voltage ⁽²⁾	I _{SD} =-1A, V _{GS} = 0V ,T _J =25°C	--	--	-0.9	V

NOTES:

1. Surface Mounted on FR4 Board, t ≤ 10 sec.

2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

Typical Performance Characteristics

Figure 1: Continuous Drain Current vs. T_c

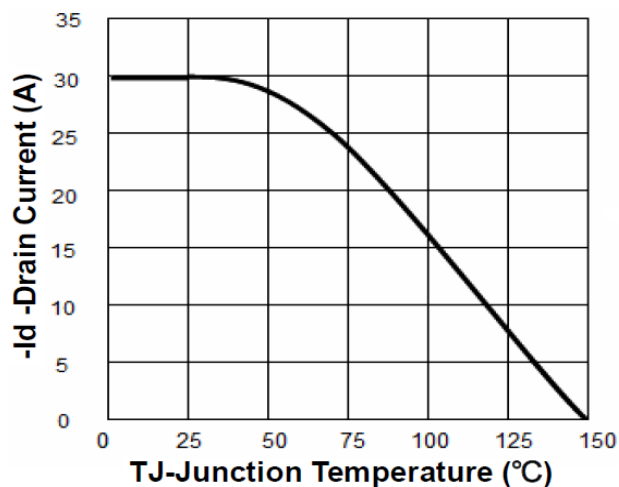


Figure 2: Normalized $R_{DS(on)}$ vs. T_J

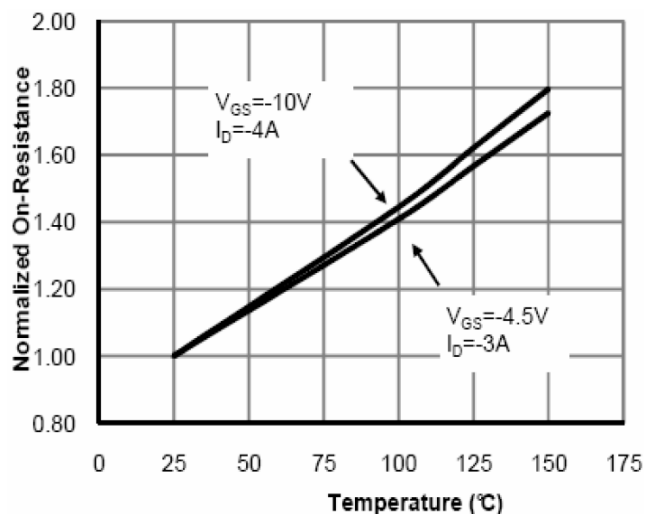


Figure 3: Normalized V_{th} vs. T_J

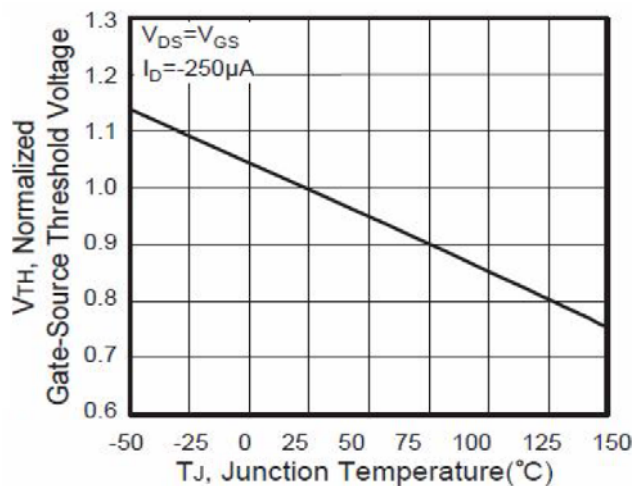


Figure 4: Gate Charge Waveform

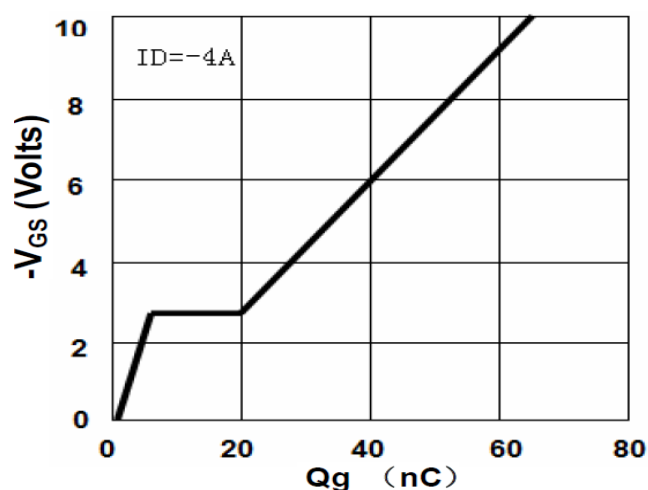


Figure 5: Capacitance

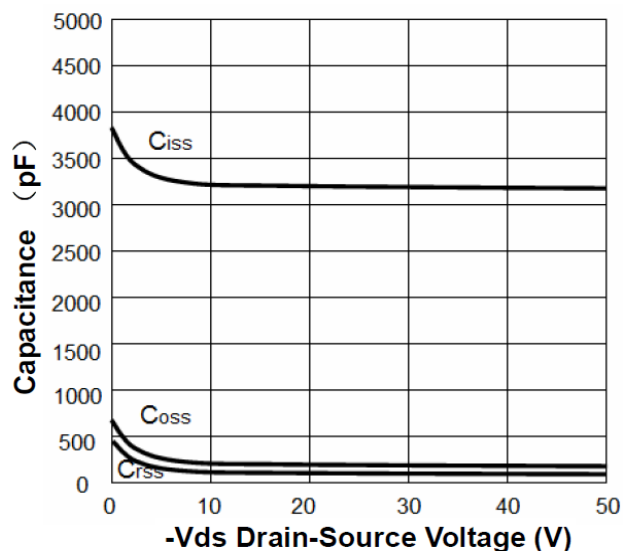


Figure 6: Maximum Safe Operation Area

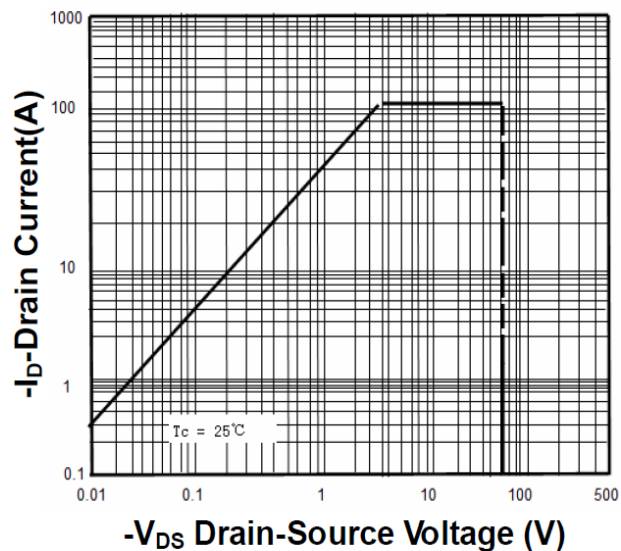


Figure 7: Switching Time Waveform

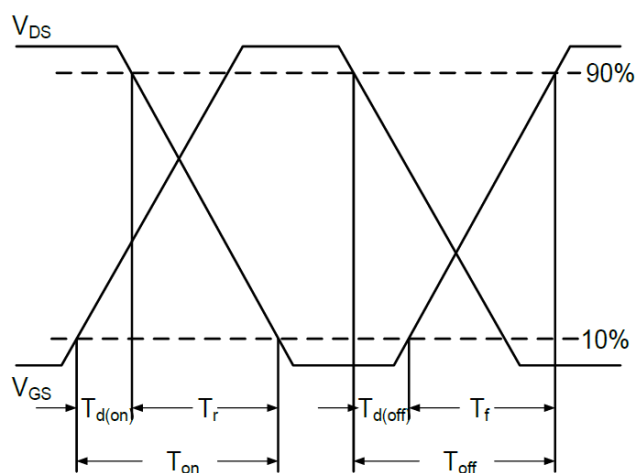
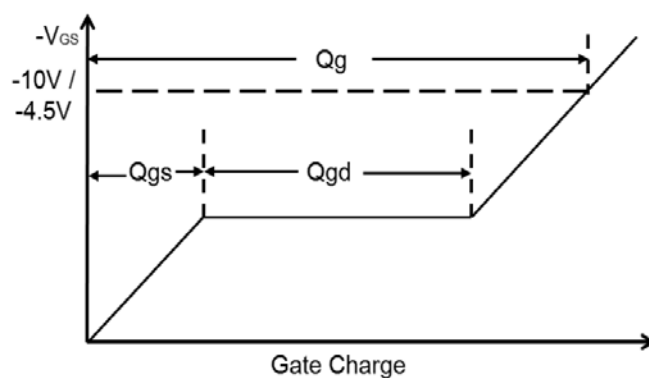
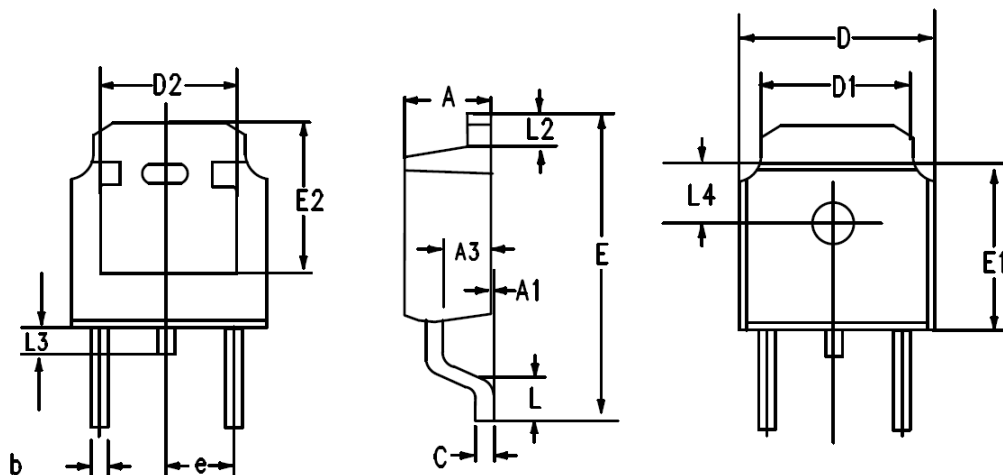


Figure 8: Gate Charge Waveform



PACKAGE MECHANICAL DATA

TO-252 Package Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
A3	1.020	1.120	0.040	0.044
b	0.740	0.820	0.029	0.032
c	0.510	0.580	0.020	0.023
D	6.500	6.700	0.256	0.263
D1	5.200	5.400	0.205	0.213
D2	4.830REF.		0.190REF.	
E	9.900	10.300	0.390	0.405
E1	6.000	6.200	0.236	0.244
E2	5.300 REF.		0.208 REF.	
e	2.286TYP.		0.090 TYP.	
L	1.400	1.600	0.055	0.063
L2	0.900	1.250	0.035	0.049
L3	0.600	1.000	0.024	0.039
L4	1.700	1.900	0.066	0.075